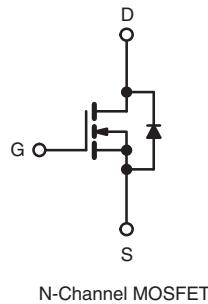
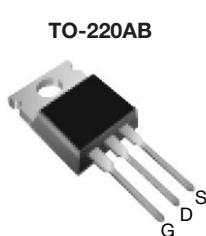


D Series Power MOSFET

PRODUCT SUMMARY	
V_{DS} (V) at T_J max.	450
$R_{DS(on)}$ max. at 25 °C (Ω)	$V_{GS} = 10$ V 0.17
Q_g max. (nC)	88
Q_{gs} (nC)	12
Q_{gd} (nC)	23
Configuration	Single



ORDERING INFORMATION

Package	TO-220AB
Lead (Pb)-free	SiHP25N40D-E3
Lead (Pb)-free and Halogen-free	SiHP25N40D-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	400	V
Gate-Source Voltage	V_{GS}	± 30	
Gate-Source Voltage AC ($f > 1$ Hz)		30	
Continuous Drain Current ($T_J = 150$ °C)	I_D	25	A
V_{GS} at 10 V		16	
$T_C = 25$ °C			
Pulsed Drain Current ^a	I_{DM}	78	
Linear Derating Factor		2.2	W/°C
Single Pulse Avalanche Energy ^b	E_{AS}	556	mJ
Maximum Power Dissipation	P_D	278	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	°C
Drain-Source Voltage Slope	dV/dt	24	V/ns
Reverse Diode dV/dt ^d		0.6	
Soldering Recommendations (Peak Temperature)	for 10 s	300 ^c	°C

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 2.3$ mH, $R_g = 25$ Ω, $I_{AS} = 17$ A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$, starting $T_J = 25$ °C.



FEATURES

- Optimal Design
 - Low Area Specific On-Resistance
 - Low Input Capacitance (C_{iss})
 - Reduced Capacitive Switching Losses
 - High Body Diode Ruggedness
 - Avalanche Energy Rated (UIS)
- Optimal Efficiency and Operation
 - Low Cost
 - Simple Gate Drive Circuitry
 - Low Figure-of-Merit (FOM): $R_{on} \times Q_g$
 - Fast Switching
- Compliant to RoHS Directive 2011/65/EU

Note

* Pb containing terminations are not RoHS compliant, exemptions may apply

APPLICATIONS

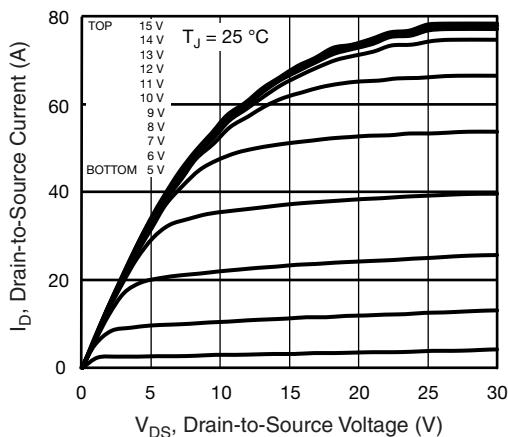
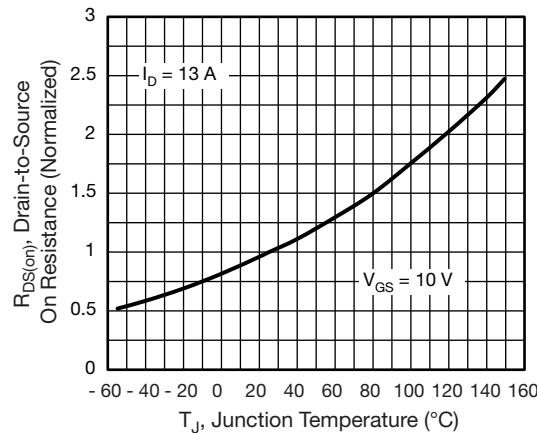
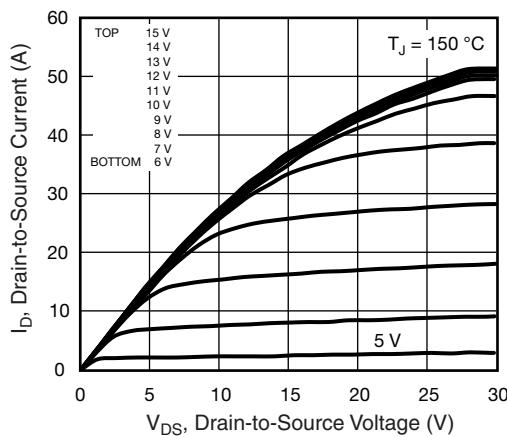
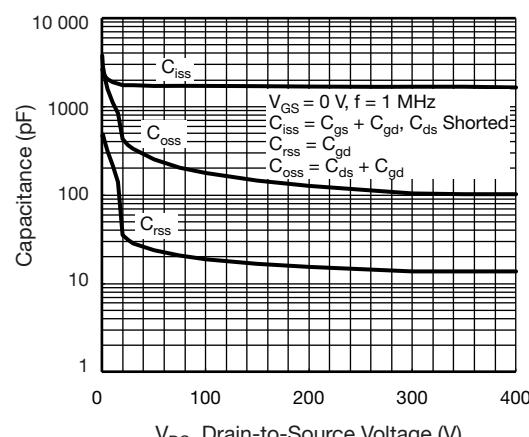
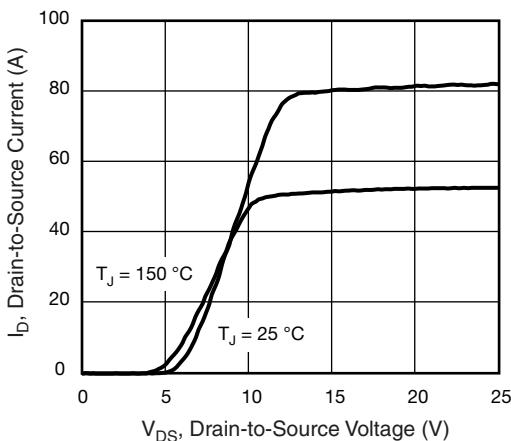
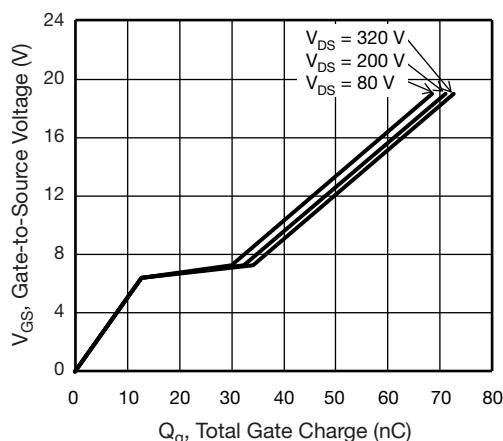
- Consumer Electronics
 - Displays (LCD or Plasma TV)
- Lighting
- Industrial
 - Welding
 - Induction Heating
 - Motor Drives
 - Battery Chargers
- SMPS

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	$^{\circ}\text{C}/\text{W}$
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.45	

SPECIFICATIONS ($T_J = 25^{\circ}\text{C}$, unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static								
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$		400	-	-	V	
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25°C , $I_D = 250 \mu\text{A}$		-	0.5	-	$^{\circ}\text{C}/\text{V}$	
Gate-Source Threshold Voltage (N)	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$		3	-	5	V	
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 30 \text{ V}$		-	-	± 100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 400 \text{ V}$, $V_{GS} = 0 \text{ V}$		-	-	1	μA	
		$V_{DS} = 320 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 125^{\circ}\text{C}$		-	-	10		
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10 \text{ V}$	$I_D = 13 \text{ A}$	-	0.14	0.17	Ω	
Forward Transconductance	g_{fs}	$V_{DS} = 50 \text{ V}$, $I_D = 13 \text{ A}$		-	7.4	-	S	
Dynamic								
Input Capacitance	C_{iss}	$V_{GS} = 0 \text{ V}$, $V_{DS} = 100 \text{ V}$, $f = 1 \text{ MHz}$		-	1707	-	pF	
Output Capacitance	C_{oss}			-	177	-		
Reverse Transfer Capacitance	C_{rss}			-	19	-		
Total Gate Charge	Q_g	$V_{GS} = 10 \text{ V}$	$I_D = 13 \text{ A}$, $V_{DS} = 320 \text{ V}$	-	44	88	nC	
Gate-Source Charge	Q_{gs}			-	12	-		
Gate-Drain Charge	Q_{gd}			-	23	-		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 320 \text{ V}$, $I_D = 13 \text{ A}$, $V_{GS} = 10 \text{ V}$, $R_g = 24.6 \Omega$		-	21	42	ns	
Rise Time	t_r			-	57	86		
Turn-Off Delay Time	$t_{d(off)}$			-	40	80		
Fall Time	t_f			-	37	74		
Gate Input Resistance	R_g	$f = 1 \text{ MHz}$, open drain		-	1.8	-	Ω	
Drain-Source Body Diode Characteristics								
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	24	A	
Pulsed Diode Forward Current	I_{SM}			-	-	78		
Diode Forward Voltage	V_{SD}	$T_J = 25^{\circ}\text{C}$, $I_S = 13 \text{ A}$, $V_{GS} = 0 \text{ V}$		-	-	1.2	V	
Reverse Recovery Time	t_{rr}	$T_J = 25^{\circ}\text{C}$, $I_F = I_S = 13 \text{ A}$, $dI/dt = 100 \text{ A}/\mu\text{s}$, $V_R = 20 \text{ V}$		-	353	-	ns	
Reverse Recovery Charge	Q_{rr}			-	4.4	-		
Reverse Recovery Current	I_{RRM}			-	24	-	A	

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Fig. 1 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature

Fig. 2 - Typical Output Characteristics

Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

Fig. 3 - Typical Transfer Characteristics

Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

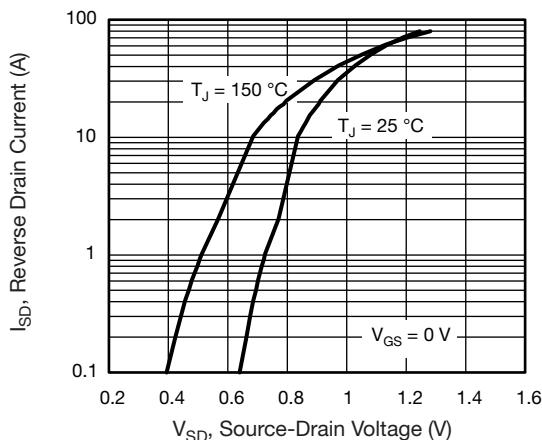


Fig. 7 - Typical Source-Drain Diode Forward Voltage

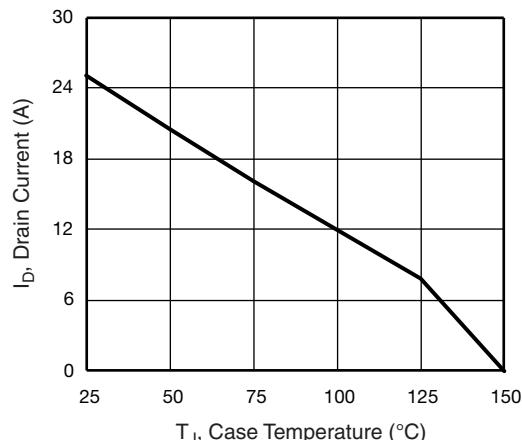


Fig. 9 - Maximum Drain Current vs. Case Temperature

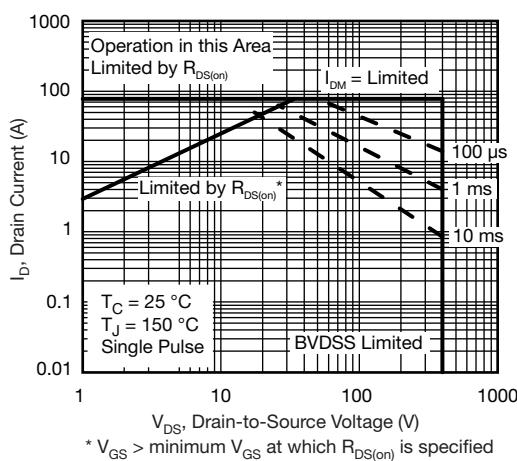


Fig. 8 - Maximum Safe Operating Area

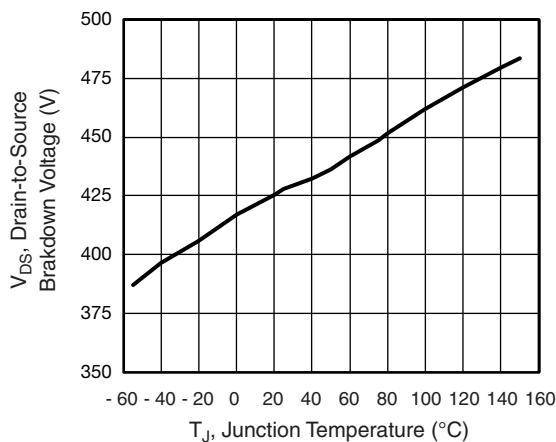


Fig. 10 - Temperature vs. Drain-to-Source Voltage

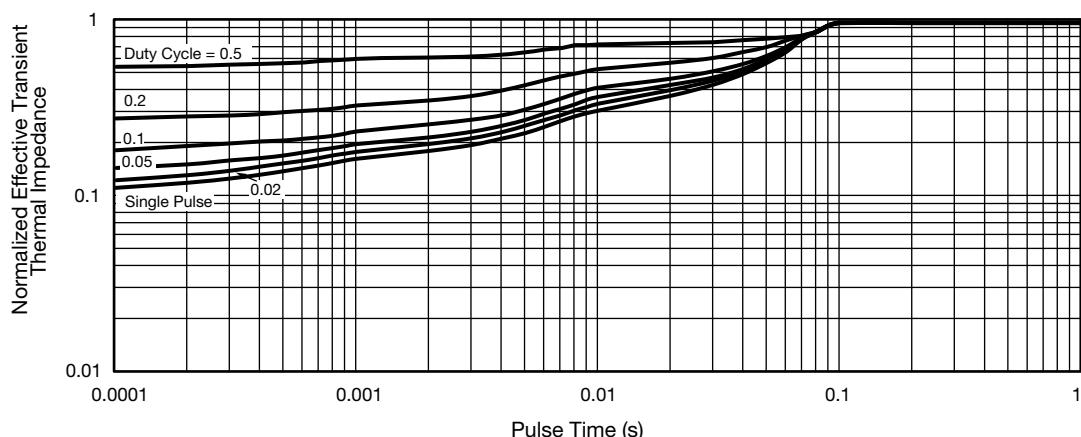


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

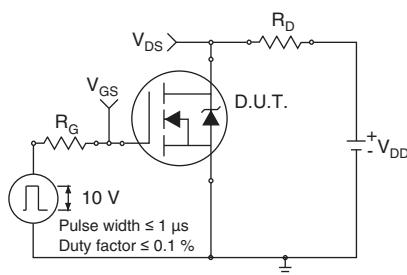


Fig. 12 - Switching Time Test Circuit

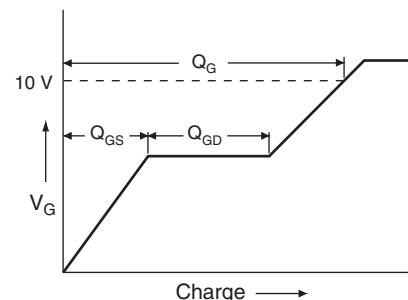


Fig. 16 - Basic Gate Charge Waveform

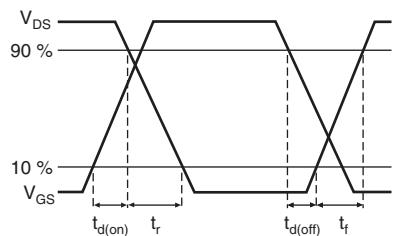


Fig. 13 - Switching Time Waveforms

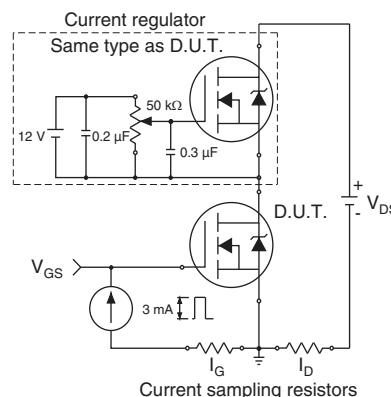


Fig. 17 - Gate Charge Test Circuit

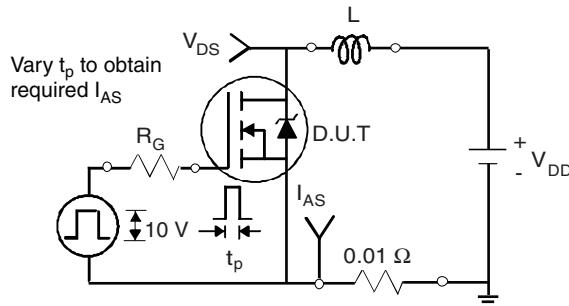


Fig. 14 - Unclamped Inductive Test Circuit

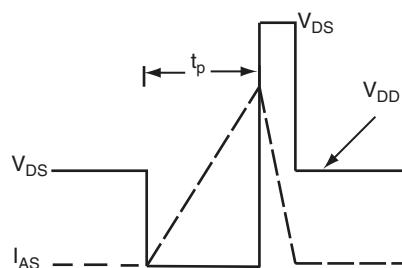
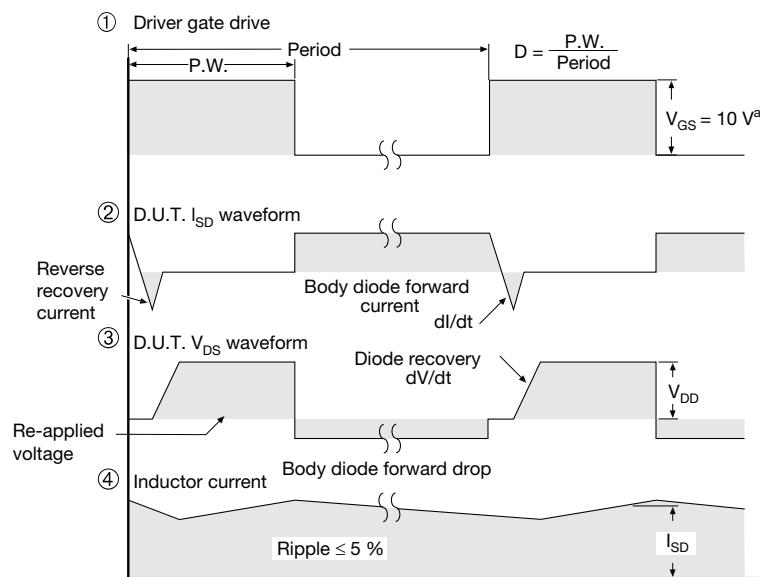
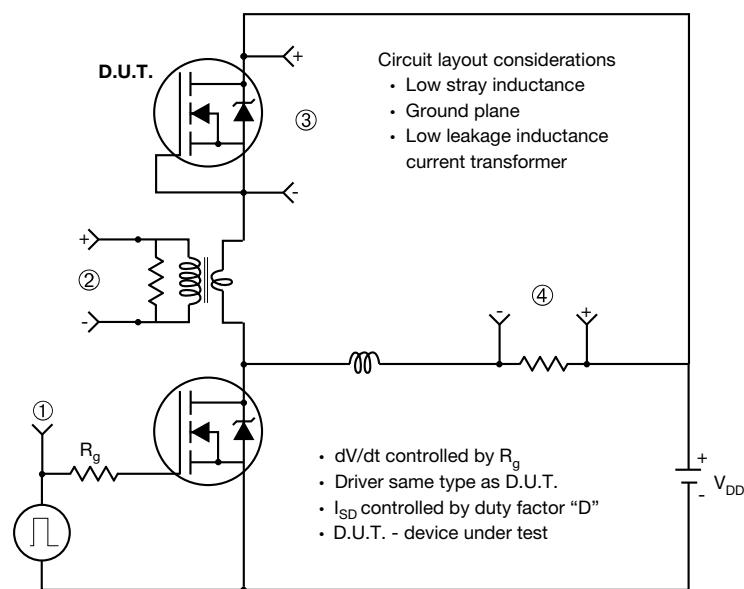
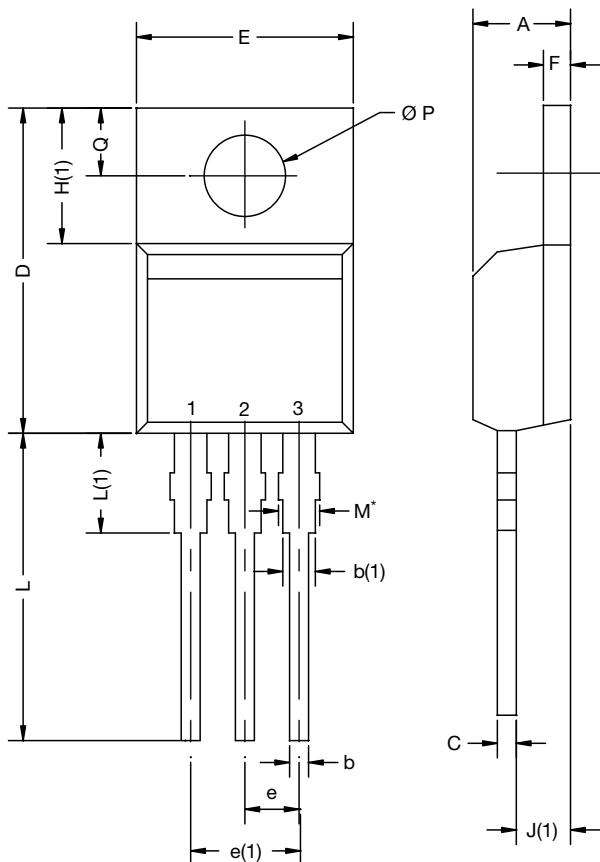


Fig. 15 - Unclamped Inductive Waveforms

Peak Diode Recovery dV/dt Test Circuit

Fig. 18 - For N-Channel

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TO-220-1



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
Ø P	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

ECN: X15-0364-Rev. C, 14-Dec-15
DWG: 6031

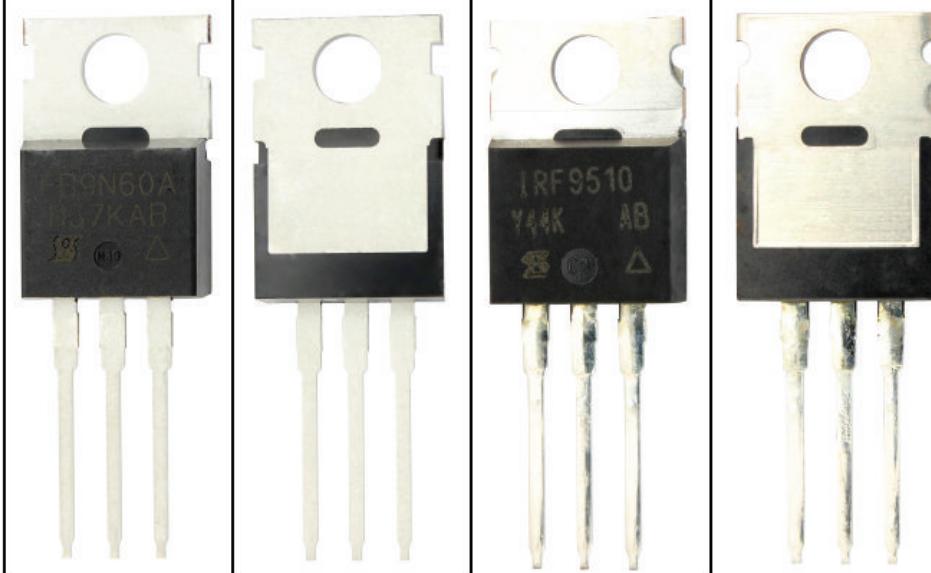
Note

- $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

Package Picture

ASE

Xi'an



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